

MA4X1600G

Silicon epitaxial planar type

For high-speed switching circuits

■ Features

- Two isolated elements are contained in one package, allowing high-density mounting
- Centrosymmetrical wiring, allowing to free from the taping direction
- Short reverse recovery time t_{rr}
- Small terminal capacitance C_t

■ Package

- Code
Mini4-G3
- Pin Name
1: Cathode 1
2: Anode 2
3: Cathode 2
4: Anode 1

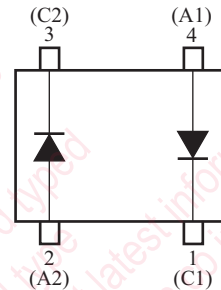
■ Absolute Maximum Ratings $T_a = 25^\circ\text{C}$

Parameter	Symbol	Rating	Unit
Reverse voltage	V_R	40	V
Maximum peak reverse voltage	V_{RM}	40	V
Forward current (Average)	Single	$I_{F(AV)}$	mA
	Series		
Repetitive peak forward current	Single	I_{FRM}	mA
	Series		
Non-repetitive peak forward surge current *	Single	I_{FSM}	mA
	Series		
Junction temperature	T_j	150	$^\circ\text{C}$
Storage temperature	T_{stg}	-55 to +150	$^\circ\text{C}$

Note) *: $t = 1\text{ s}$

■ Marking Symbol: M1D

■ Internal Connection



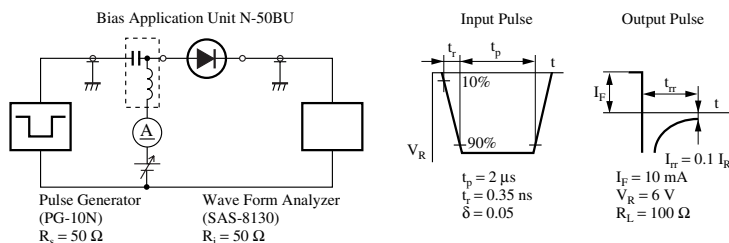
■ Electrical Characteristics $T_a = 25^\circ\text{C} \pm 3^\circ\text{C}$

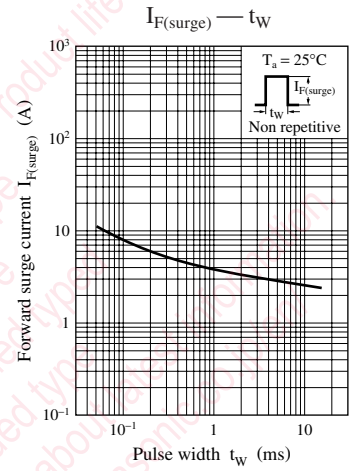
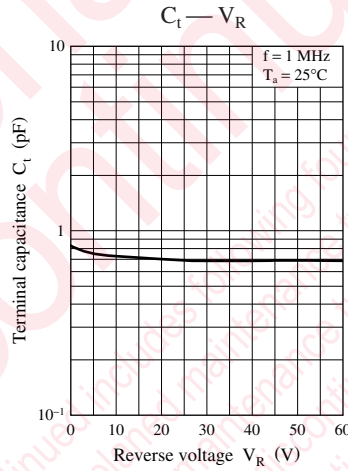
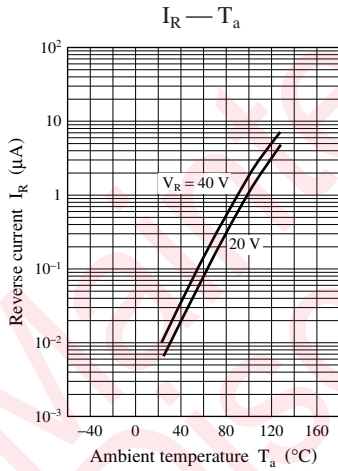
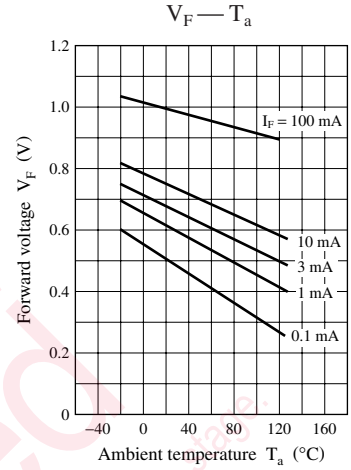
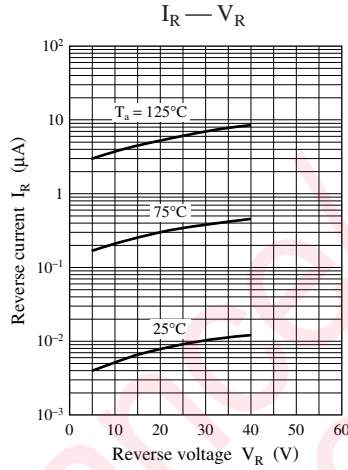
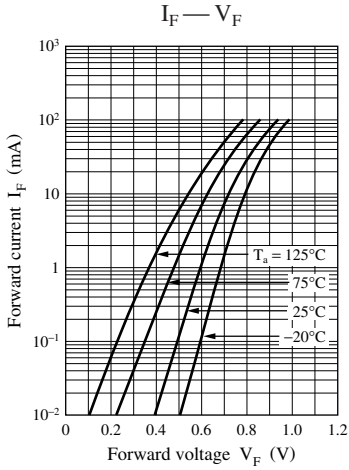
Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Forward voltage	V_F	$I_F = 100\text{ mA}$		0.95	1.20	V
Reverse voltage	V_R	$I_R = 100\ \mu\text{A}$	40			V
Reverse current	I_R	$V_R = 35\text{ V}$			0.1	μA
Terminal capacitance	C_t	$V_R = 0\text{ V}, f = 1\text{ MHz}$		0.9	2.0	pF
Reverse recovery time *	t_{rr}	$I_F = 10\text{ mA}, V_R = 6\text{ V}$ $I_{tr} = 0.1 I_R, R_L = 100\ \Omega$			3	ns

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring method for diodes.

2. Absolute frequency of input and output is 100 MHz.

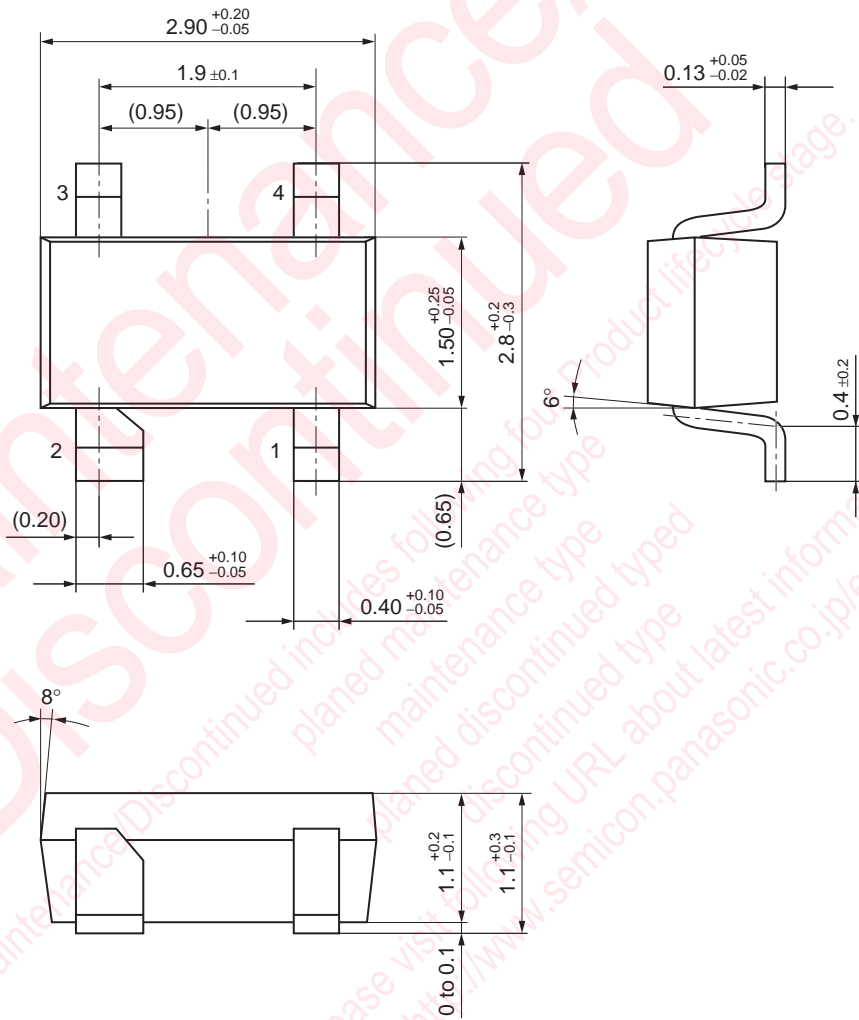
3. *: t_{rr} measurement circuit





Mini4-G3

Unit: mm



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